

TOSHIBA IGBT Module Silicon N Channel IGBT

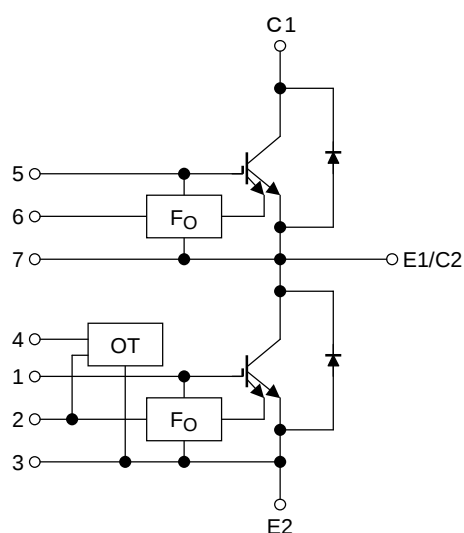
# MG400Q2YS60A

High Power Switching Applications

Motor Control Applications

- Integrates a complete half bridge power circuit and fault-signal output circuit in one package.  
(short circuit and over temperature)
- The electrodes are isolated from case.
- Low thermal resistance.
- $V_{CE(sat)} = 2.4\text{ V (typ.)}$

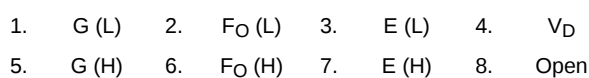
## Equivalent Circuit



Signal terminal

|    |       |    |                    |    |       |    |                |
|----|-------|----|--------------------|----|-------|----|----------------|
| 1. | G (L) | 2. | F <sub>O</sub> (L) | 3. | E (L) | 4. | V <sub>D</sub> |
| 5. | G (H) | 6. | F <sub>O</sub> (H) | 7. | E (H) | 8. | Open           |

## Unit: mm



Technical drawing of a rectangular plate with dimensions and hole locations. The plate has a total width of 25.4 ± 0.6 mm and a total height of 25.4 mm. The drawing shows a central horizontal dashed line. The top half contains two circular holes, each with a diameter of 2.54 mm, located at a distance of 2.54 mm from the top edge. The bottom half contains two circular holes, each with a diameter of 2.54 mm, located at a distance of 2.54 mm from the bottom edge. The distance between the centers of the two holes in each row is 2.54 mm. The distance between the centers of the two rows of holes is 25.4 mm.

1. G (L)
2. F<sub>O</sub> (L)
3. E (L)
4. V<sub>D</sub>
5. G (H)
6. F<sub>O</sub> (H)
7. E (H)
8. Open

Weight: 375 g

## Maximum Ratings (Ta = 25°C)

| Stage    | Characteristics                         |      | Symbol     | Rating          | Unit |
|----------|-----------------------------------------|------|------------|-----------------|------|
| Inverter | Collector-emitter voltage               |      | $V_{CES}$  | 1200            | V    |
|          | Gate-emitter voltage                    |      | $V_{GES}$  | $\pm 20$        | V    |
|          | Collector current                       | DC   | $I_C$      | 400             | A    |
|          |                                         | 1 ms | $I_{CP}$   | 800             |      |
|          | Forward current                         | DC   | $I_F$      | 400             | A    |
|          |                                         | 1 ms | $I_{FM}$   | 800             |      |
|          | Collector power dissipation (Tc = 25°C) |      | $P_C$      | 3750            | W    |
| Control  | Control voltage (OT)                    |      | $V_D$      | 20              | V    |
|          | Fault input voltage                     |      | $V_{FO}$   | 20              | V    |
|          | Fault input current                     |      | $I_{FO}$   | 20              | mA   |
| Module   | Junction temperature                    |      | $T_j$      | 150             | °C   |
|          | Storage temperature range               |      | $T_{stg}$  | -40~125         | °C   |
|          | Operation temperature range             |      | $T_{ope}$  | -20~100         | °C   |
|          | Isolation voltage                       |      | $V_{isol}$ | 2500 (AC 1 min) | V    |
|          | Screw torque                            |      | —          | 3 (M5)          | N·m  |

## Electrical Characteristics (Tj = 25°C)

## 1. Inverter stage

| Characteristics                      |                        | Symbol                 | Test Condition                                                                                                          | Min  | Typ.  | Max   | Unit          |
|--------------------------------------|------------------------|------------------------|-------------------------------------------------------------------------------------------------------------------------|------|-------|-------|---------------|
| Gate leakage current                 | $I_{GES}$              |                        | $V_{GE} = \pm 20 \text{ V}, V_{CE} = 0$                                                                                 | —    | —     | +3/-4 | mA            |
|                                      |                        |                        | $V_{GE} = +10 \text{ V}, V_{CE} = 0$                                                                                    | —    | —     | 100   | nA            |
| Collector cut-off current            |                        | $I_{CES}$              | $V_{CE} = 1200 \text{ V}, V_{GE} = 0$                                                                                   | —    | —     | 1.0   | mA            |
| Gate-emitter cut-off voltage         |                        | $V_{GE} \text{ (off)}$ | $V_{CE} = 5 \text{ V}, I_C = 400 \text{ mA}$                                                                            | 6.0  | 7.0   | 8.0   | V             |
| Collector-emitter saturation voltage | $V_{CE} \text{ (sat)}$ |                        | $V_{GE} = 15 \text{ V}, I_C = 400 \text{ A}$                                                                            | —    | 2.4   | 2.8   | V             |
|                                      |                        |                        | $T_j = 125^\circ\text{C}$                                                                                               | —    | —     | 3.2   |               |
| Input capacitance                    |                        | $C_{ies}$              | $V_{CE} = 10 \text{ V}, V_{GE} = 0, f = 1 \text{ MHz}$                                                                  | —    | 31000 | —     | pF            |
| Switching time                       | Turn-on delay time     | $t_d \text{ (on)}$     | $V_{CC} = 600 \text{ V}, I_C = 400 \text{ A}$<br>$V_{GE} = \pm 15 \text{ V}, R_G = 5.1 \Omega$<br>(See page 4) (Note 1) | 0.10 | —     | 1.00  | $\mu\text{s}$ |
|                                      | Turn-off time          | $t_{off}$              |                                                                                                                         | —    | —     | 2.00  |               |
|                                      | Fall time              | $t_f$                  |                                                                                                                         | —    | —     | 0.50  |               |
| Reverse recovery time                |                        | $t_{rr}$               |                                                                                                                         | —    | —     | 0.50  |               |
| Forward voltage                      |                        | $V_F$                  | $I_F = 400 \text{ A}$                                                                                                   | —    | 2.4   | 2.8   | V             |

Note 1: Switching time test circuit &amp; timing chart

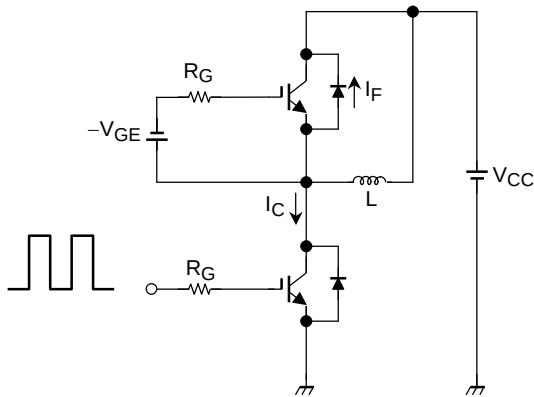
## 2. Control (Tc = 25°C)

| Characteristics         | Symbol             | Test Condition                                      | Min | Typ. | Max | Unit          |
|-------------------------|--------------------|-----------------------------------------------------|-----|------|-----|---------------|
| Fault output current    | OC                 | $V_{GE} = 15 \text{ V}$                             | 480 | —    | —   | A             |
| Over temperature        | OT                 | —                                                   | 100 | —    | 125 | °C            |
| Fault output delay time | $t_d \text{ (Fo)}$ | $V_{CC} = 600 \text{ V}, V_{GE} = \pm 15 \text{ V}$ | —   | —    | 8   | $\mu\text{s}$ |

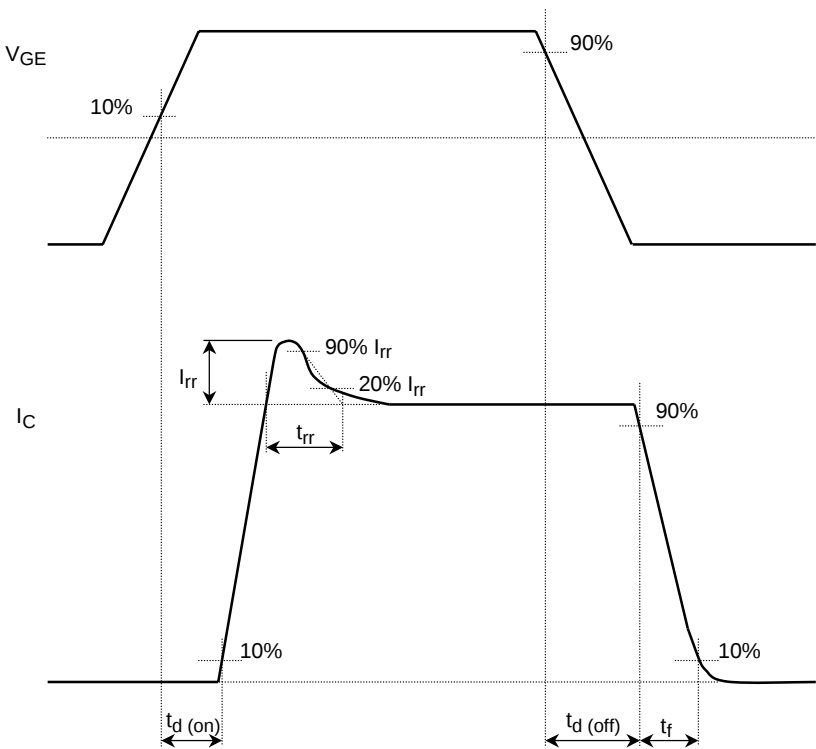
3. Module (Tc = 25°C)

| Characteristics                     | Symbol        | Test Condition        | Min | Typ.  | Max   | Unit |
|-------------------------------------|---------------|-----------------------|-----|-------|-------|------|
| Junction to case thermal resistance | $R_{th(j-c)}$ | Inverter IGBT stage   | —   | —     | 0.033 | °C/W |
|                                     |               | Inverter FRD stage    | —   | —     | 0.068 |      |
| Case to fin thermal resistance      | $R_{th(c-f)}$ | With silicon compound | —   | 0.013 | —     | °C/W |

Switching Time Test Circuit



Timing Chart



## Remark

## &lt;Short circuit capability condition &gt;

- Short circuit capability is 6  $\mu$ s after fault output signal.  
Please keep following condition to use fault output signal.
  - $V_{CC} \leq 750$  V
  - $14.8$  V  $\leq V_{GE} \leq 17.0$  V
  - $R_G \geq 5.1$   $\Omega$
  - $T_j \leq 125^\circ\text{C}$

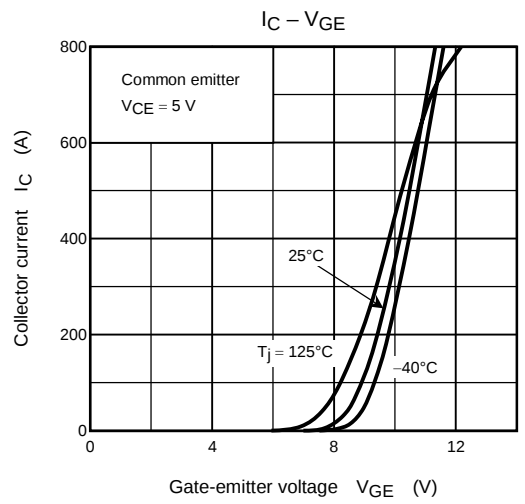
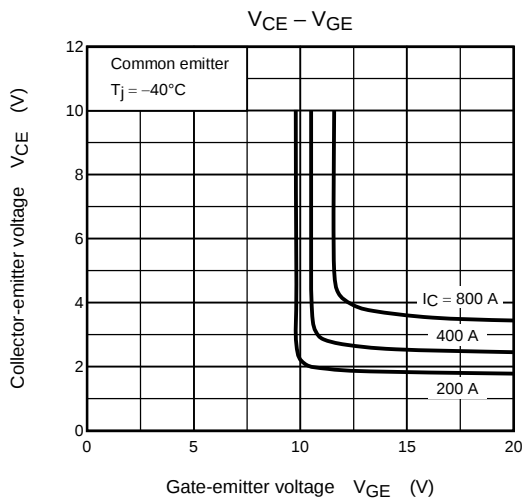
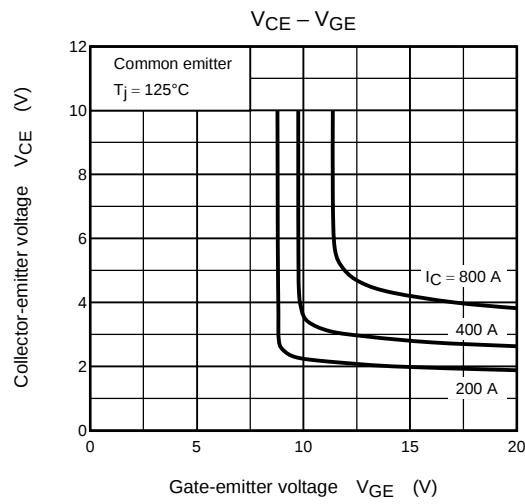
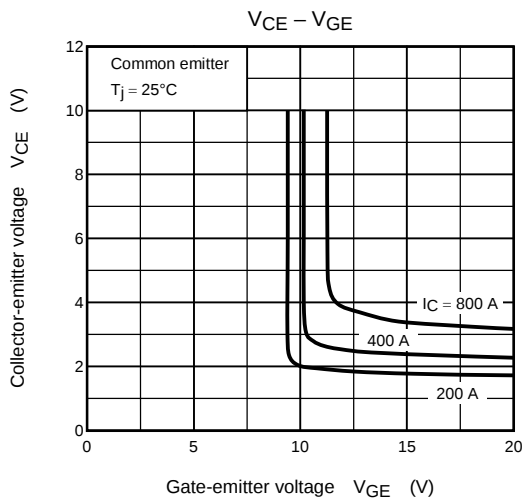
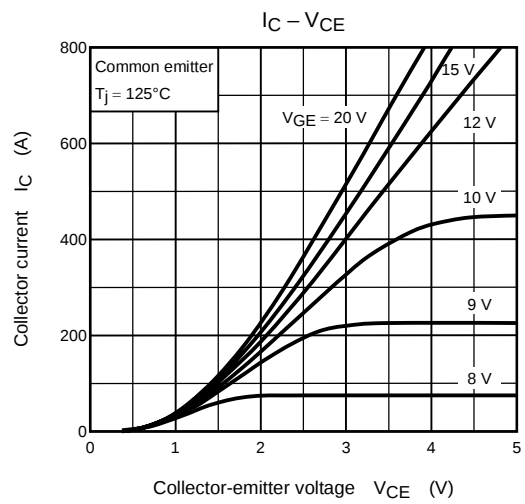
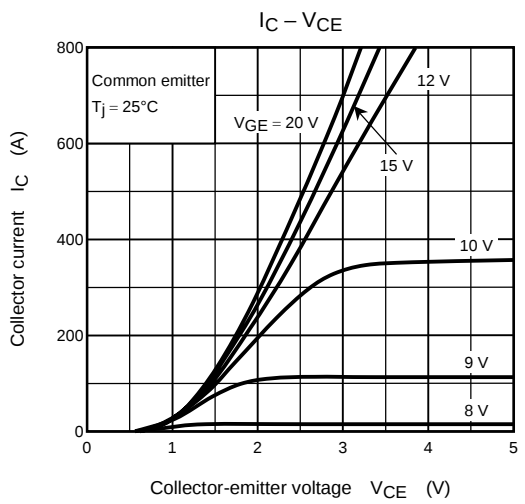
## &lt;Gate voltage &gt;

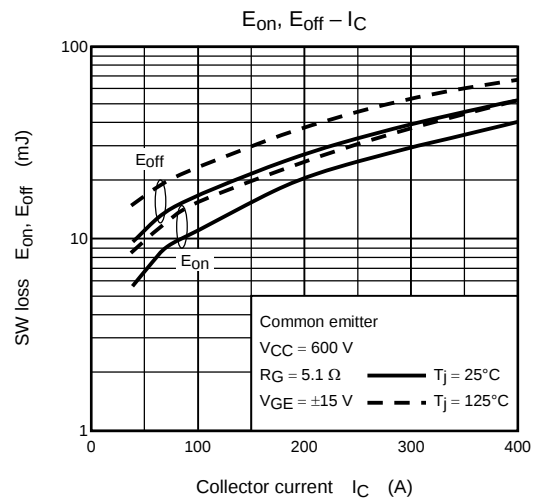
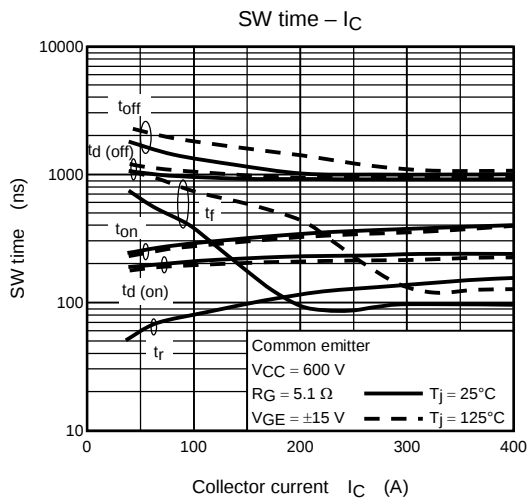
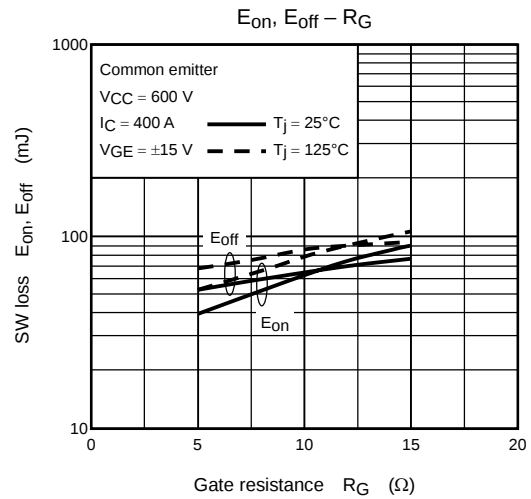
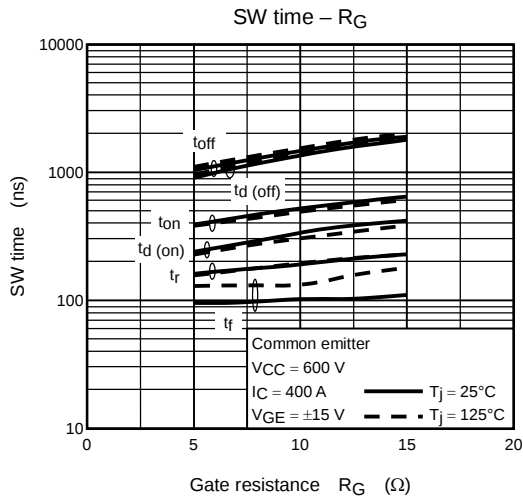
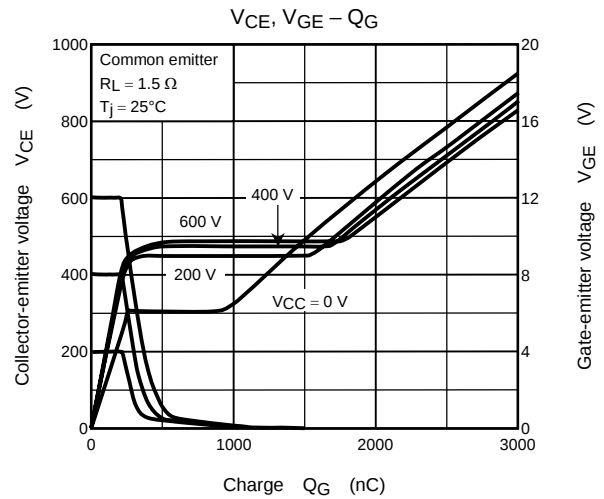
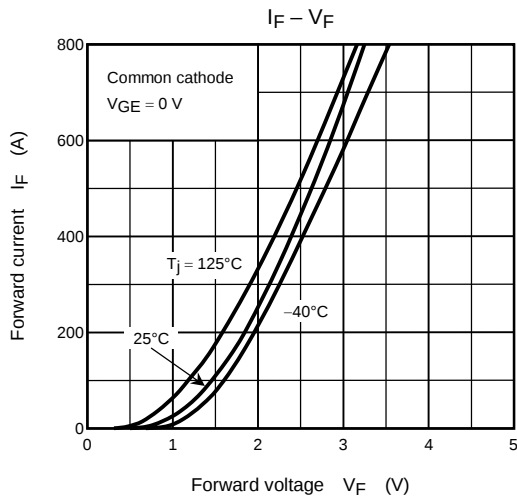
- To use this product,  $V_{GE}$  must be provided higher than 14.8 V  
In case  $V_{GE}$  is less than 14.8 V, fault signal FO may not be output even under error conditions.

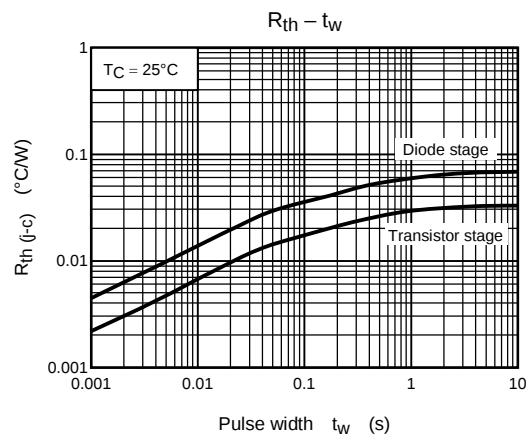
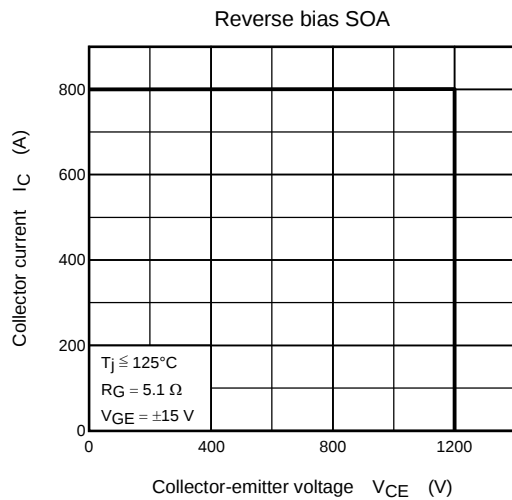
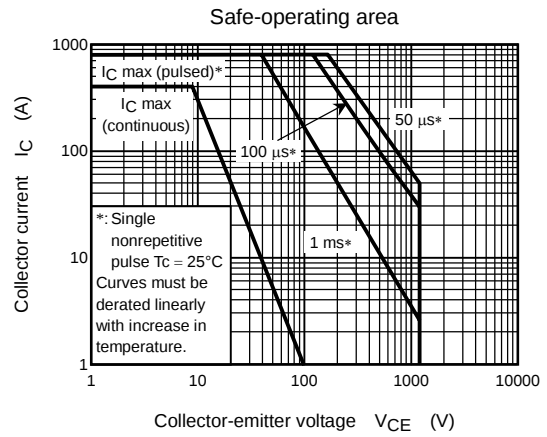
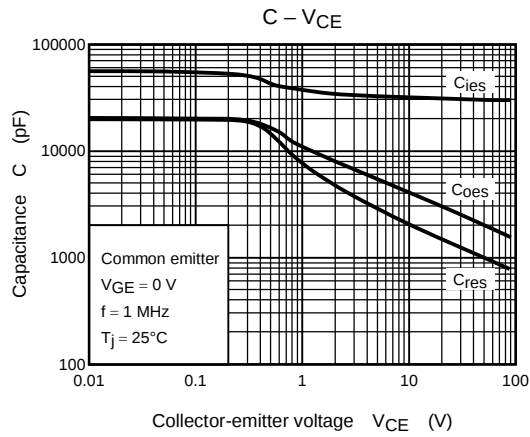
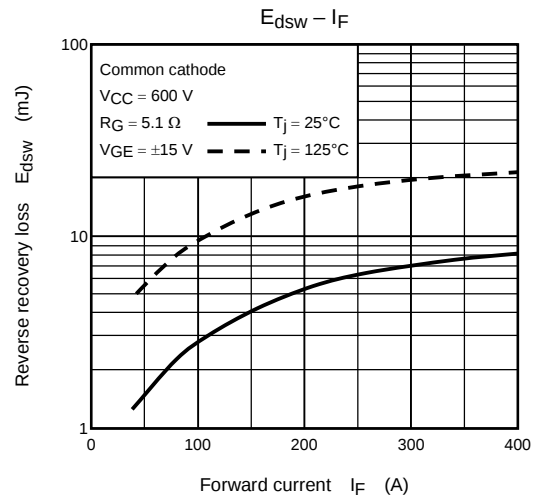
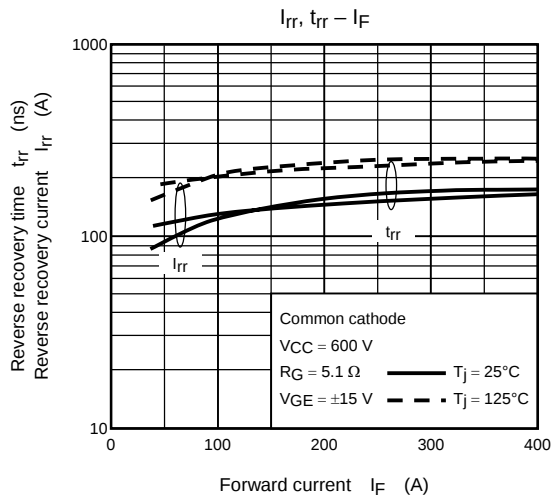
## &lt;For parallel use&gt;

- For parallel use of this product, please use the same rank for both  $V_{CE(sat)}$  and  $V_F$  among IGBT in parallel without fail.

| $V_{CE(sat)}$ | $V_F$ | Min | Max |
|---------------|-------|-----|-----|
| 24            | E     | 2.1 | 2.4 |
| 26            | F     | 2.3 | 2.6 |
| 28            | G     | 2.5 | 2.8 |







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